

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3154337

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the SPELLING OF THE LAST NAME OF THE 5TH ASSIGNOR FROM "BANK" TO "BANG" previously recorded on Reel 033734 Frame 0231. Assignor(s) hereby confirms the ASSIGNMENT.

CONVEYING PARTY DATA

Name	Execution Date
HYE YEON CHA	08/08/2014
DONG HWAN LEE	08/08/2014
JUNG HYUK JUNG	08/08/2014
CHAN YOON	08/08/2014
HYE MIN BANG	08/08/2014
TAE YOUNG KIM	08/08/2014

RECEIVING PARTY DATA

Name:	SAMSUNG ELECTRO-MECHANICS CO., LTD.
Street Address:	MAEYOUNG-RO 150 (MAETAN-DONG), YOUNGTONG-GU
City:	SUWON-SI, GYEONGGI-DO
State/Country:	KOREA, REPUBLIC OF

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14485402

CORRESPONDENCE DATA**Fax Number:**

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 202-756-8000

Email: ipdocketmwe@mwe.com, gdamianoszafran@mwe.com

Correspondent Name: MCDERMOTT WILL & EMERY LLP

Address Line 1: 500 NORTH CAPITOL STREET

Address Line 4: WASHINGTON, D.C. 20001

ATTORNEY DOCKET NUMBER:	093814-0502
NAME OF SUBMITTER:	GLENN S. DAMIANO-SZAFRAN
SIGNATURE:	/Glenn S. Damiano-Szafran/
DATE SIGNED:	12/18/2014

Total Attachments: 5

PATENT

source=090104-0502_ASSIGN_DEC#page1.tif

source=090104-0502_ASSIGN_DEC#page2.tif

source=090104-0502_ASSIGN_DEC#page3.tif

source=090104-0502_ASSIGN_DEC#page4.tif

source=090104-0502_ASSIGN_DEC#page5.tif



United States Patent and Trademark Office

Home | Site Index | Search | Guides | Contacts | eBusiness | eBiz alerts | News | Help



Electronic Patent Assignment System

Confirmation Receipt

Your assignment has been received by the USPTO.
The coversheet of the assignment is displayed below:

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>HYE YEON CHA</td> <td>08/08/2014</td> </tr> <tr> <td>DONG HWAN LEE</td> <td>08/08/2014</td> </tr> <tr> <td>JUNG HYUK JUNG</td> <td>08/08/2014</td> </tr> <tr> <td>CHAN YOON</td> <td>08/08/2014</td> </tr> <tr> <td>HYE MIN BANK</td> <td>08/08/2014</td> </tr> <tr> <td>TAE YOUNG KIM</td> <td>08/08/2014</td> </tr> </tbody> </table>		Name	Execution Date	HYE YEON CHA	08/08/2014	DONG HWAN LEE	08/08/2014	JUNG HYUK JUNG	08/08/2014	CHAN YOON	08/08/2014	HYE MIN BANK	08/08/2014	TAE YOUNG KIM	08/08/2014
Name	Execution Date														
HYE YEON CHA	08/08/2014														
DONG HWAN LEE	08/08/2014														
JUNG HYUK JUNG	08/08/2014														
CHAN YOON	08/08/2014														
HYE MIN BANK	08/08/2014														
TAE YOUNG KIM	08/08/2014														
RECEIVING PARTY DATA															
Name:	SAMSUNG ELECTRO-MECHANICS CO., LTD.														
Street Address:	MAEYOUNG-RO 150 (MAETAN-DONG), YOUNGTONG-GU														
City:	SUWON-SI, GYEONGGI-DO														
State/Country:	KOREA, REPUBLIC OF														
PROPERTY NUMBERS Total: 1															
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14485402</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14485402										
Property Type	Number														
Application Number:	14485402														

CORRESPONDENCE DATA

Fax Number:

Phone: 202-756-8000

Email: mweipdocket@mwe.com

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Correspondent Name: MCDERMOTT WILL & EMERY LLP

Address Line 1: THE MCDERMOTT BUILDING

Address Line 2: 500 NORTH CAPITOL STREET, N.W.

Address Line 4: WASHINGTON, D.C. 20001

ATTORNEY DOCKET NUMBER:

093814-0502

NAME OF SUBMITTER:

STEPHEN A. BECKER, P.C.

Signature:

/Stephen A. Becker, P.C./

Date:

09/12/2014

Total Attachments: 3

source=093814-0502_DEC_ASSIGN#page1.tif

source=093814-0502_DEC_ASSIGN#page2.tif

source=093814-0502_DEC_ASSIGN#page3.tif

RECEIPT INFORMATION

EPAS ID: PAT3021269

Receipt Date: 09/12/2014

[Return to home page](#)| [HOME](#) | [INDEX](#) | [SEARCH](#) | [eBUSINESS](#) | [CONTACT US](#) | [PRIVACY STATEMENT](#)

COMBINED DECLARATION AND ASSIGNMENT FOR PATENT APPLICATION

As a below named inventor, I hereby declare that:

I believe I am the original or an original joint inventor of a claimed invention in the application for which a patent is sought on the invention entitled:

**CHIP ELECTRONIC COMPONENT AND MANUFACTURING METHOD
THEREOF**

which application is:

X attached, or

United States application number or PCT international application
number _____ filed on _____.

The above-identified application was made or authorized to be made by me.

In the event that the filing date and/or application number are not entered above at the time I execute this document, and if such information is deemed necessary, I hereby authorize and request the registered practitioners of **McDermott Will & Emery LLP**, associated with the Customer Number **20277**, to insert above the filing date and/or application number of the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

ASSIGNMENT

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I hereby assign to

SAMSUNG ELECTRO-MECHANICS CO., LTD.

having an address at **Maeyoung-Ro 150 (Maetan-Dong), Youngtong-Gu, Suwon-Si, Gyeonggi-Do, Republic of Korea**

hereinafter designated as the Assignee, the entire (100%) right, title and interest for the United States as defined in 35 USC §100, in the invention described in the application identified in this document.

I hereby confirm any prior assignment to Assignee, and to the extent that I have not already done so, agree to assign, and hereby do, sell, assign and transfer unto Assignee and its successors in interest, the full and exclusive right, title and interest in the United States of America and throughout the world, including the right to claim priority under the laws of the United States, the Paris Convention, and any foreign countries, to the inventions as described in the aforesaid application, to the aforesaid application itself, and all divisions, continuations, continuations-in-part, or other applications claiming priority directly or indirectly from the aforesaid application, and any United States or foreign Letters Patent, utility model, or other similar rights which may be granted thereon, including reissues, reexaminations and extensions thereof, and all copyright rights throughout the world in the aforesaid application and the subject matter disclosed therein, these rights, title and interest to be held and enjoyed by Assignee to the full end of the term for which the Letters Patent, utility model, or other similar rights, are granted and any extensions thereof as fully and entirely as the same would have been held by the undersigned had this assignment and sale not been made, and the right to sue for, and recover for past infringements of, or liabilities for, any of the rights relating to any of the applications, patents, utility models, or other similar rights, resulting therefrom, and the copyright rights;

I hereby covenant and agree to execute all instruments or documents required or requested for the making and prosecution of any applications of any type for patent, utility model, or other similar rights, and for copyright, in the United States and in all foreign countries including, but not limited to, any provisional, continuation, continuation-in-part, divisional, renewal or substitute thereof, and as to letters patent any reissue, re-examination, or extension thereof, and for litigation regarding, or for the purpose of protecting title and to the said invention, the United States application for patent, or Letters Patent therefor, and to testify in support thereof, for the benefit of Assignee without further or other compensation than that above set forth;

I hereby covenant that no assignment, sale, license, agreement or encumbrance has been or will be entered into which would conflict with this Assignment.

Legal name of first inventor Hye Yeon CHA	
First inventor's signature <i>Hye yeon Cha</i>	Date 2014. 8. 8

Legal name of second inventor Dong Hwan LEE	
Second inventor's signature <i>Lee Dong Hwan</i>	Date 2014. 8. 8

Legal name of third inventor Jung Hyuk JUNG	
Third inventor's signature <i>Jung Hyuk Jung</i>	Date 2014. 8. 8

Legal name of fourth inventor Chan YOON	
Fourth inventor's signature <i>[Signature]</i>	Date 2014. 8. 8

Legal name of fifth inventor Hye Min BANG	
Fifth inventor's signature <i>Hye Min Bang</i>	Date 2014. 8. 8

Legal name of sixth inventor Tae Young KIM	
Sixth inventor's signature <i>Kim Tae Young</i>	Date 2014. 8. 8